



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(on) max}	I _D T _C = +25°C	
700V	1.3Ω @ $V_{GS} = 10V$	4.6A	

Features and Benefits

- Low On-Resistance
- High BVDss rating for power application
- Low Input Capacitance
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(on)}) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Motor Control
- Backlighting
- AC-DC Converters

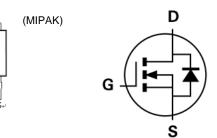
Mechanical Data

- Case: TO251
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.33 grams (Approximate)









TO251 Top View

TO251 Bottom View

Top View Pin Configuration

Internal Schematic

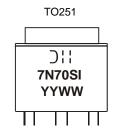
Ordering Information (Note 4)

Part Number	Case	Packaging
DMJ70H1D3SI3	TO251	75pieces / tube

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http"//www.diodes.com/products/packages.html.

Marking Information



☐ I = Manufacturer's Marking

7N70SI = Product Type Marking Code

YYWW = Date Code Marking

YY or YY= Last Digit of Year (ex: 15 = 2015)

WW or WW = Week Code (01 to 53)



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Drain-Source Voltage		V _{DSS}	700	V
Gate-Source Voltage		V _{GSS}	±30	V
Continuous Drain Current (Note 5) V _{GS} = 10V	$T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$	I _D	4.6 2.9	А
Maximum Body Diode Forward Current (Note 6)		Is	3.0	Α
Pulsed Drain Current (10µs pulse, duty cycle = 1%)		I _{DM}	5.4	A
Avalanche Current (Note 7)	L = 60mH	I _{AS}	1.1	A
Avalanche Energy (Note 7)	L = 60mH	E _{AS}	40	mJ
Peak Diode Recovery dv/dt (Note 7)		dv/dt	5	V/ns

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

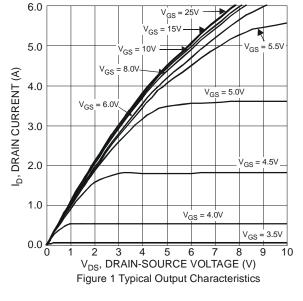
Characteristic	Symbol	Value	Units		
Total Dower Discipation (Note 5)	T _C = +25°C	D-	41	W	
Total Power Dissipation (Note 5)	T _C = +100°C	P _D	16	l vv	
Thermal Resistance, Junction to Ambient (Note 6)		$R_{\theta JA}$	79	°C/W	
Thermal Resistance, Junction to Case (Note 5)	$R_{\theta JC}$	3.0	*C/VV		
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C	

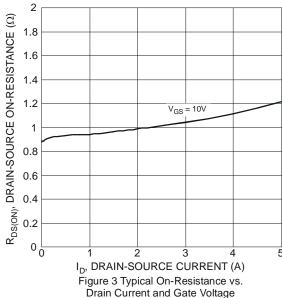
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

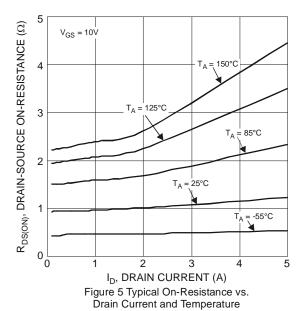
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	700	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	V _{DS} = 700V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	100	nA	$V_{GS} = \pm 30V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(th)}	2	2.9	4	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	1.0	1.3	Ω	$V_{GS} = 10V, I_D = 2.5A$	
Diode Forward Voltage	V_{SD}	_	0.9	1.3	V	$V_{GS} = 0V, I_{S} = 5A$	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	Ciss	_	351	_		$V_{DS} = 50V$, $f = 1MHz$, $V_{GS} = 0V$	
Output Capacitance	Coss	_	66	_	pF		
Reverse Transfer Capacitance	C _{rss}	_	1.1	_			
Gate Resistance	R _G	_	3.5	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Qg	_	13.9	_		V 500V I 54	
Gate-Source Charge	Q _{gs}	_	1.9	_	nC	$V_{DD} = 560V, I_D = 5A,$ $V_{GS} = 10V$	
Gate-Drain Charge	Q_{gd}	_	8.5	_			
Turn-On Delay Time	t _{D(on)}	_	8.5	_		$V_{DD} = 350V, V_{GS} = 10V,$ $R_G = 4.7\Omega, I_D = 2.5A$	
Turn-On Rise Time	t _r	_	11.6	_			
Turn-Off Delay Time	t _{D(off)}	_	24.5	_	ns		
Turn-Off Fall Time	t _f	_	10	_			
Body Diode Reverse Recovery Time	t _{rr}	_	212	_	ns	L 50 41/4/ 4000//-	
Body Diode Reverse Recovery Time (T _J = +150°C)	t _{rr}	_	251		ns		
Body Diode Reverse Recovery Charge	Q _{rr}	_	1.8		μC	$I_S = 5A$, dl/dt = 100A/ μ s	
Body Diode Reverse Recovery Charge (T _J = +150°C)	Q _{rr}	_	2.3	_	μC		

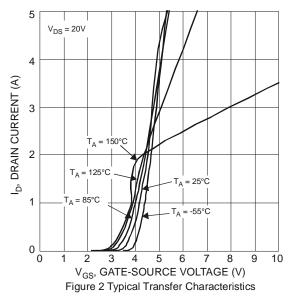
- 5. Device mounted on infinite heatsink.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
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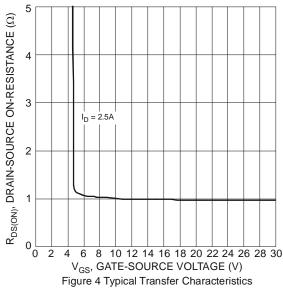












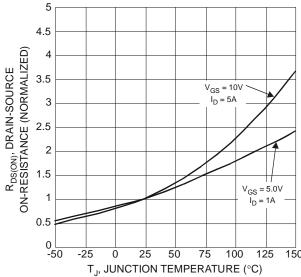
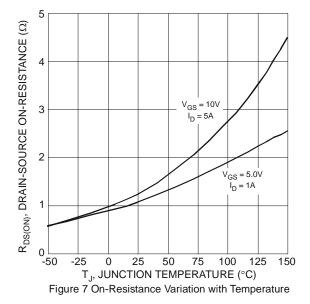
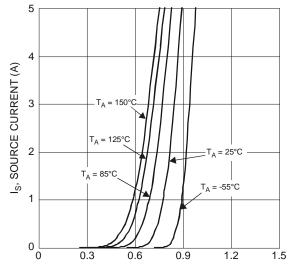


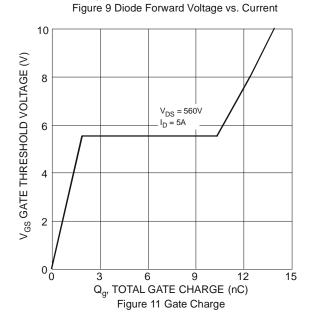
Figure 6 On-Resistance Variation with Temperature







V_{SD}, SOURCE-DRAIN VOLTAGE (V)



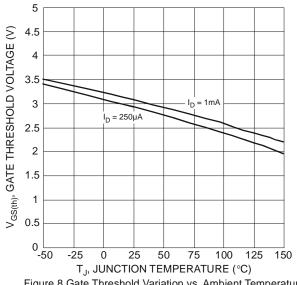
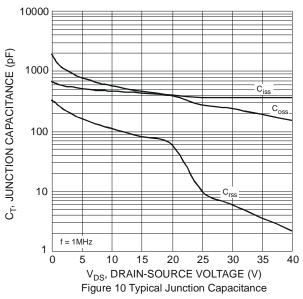
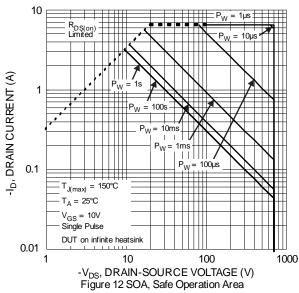
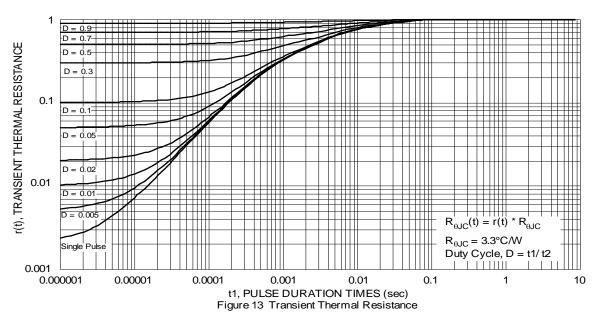


Figure 8 Gate Threshold Variation vs. Ambient Temperature



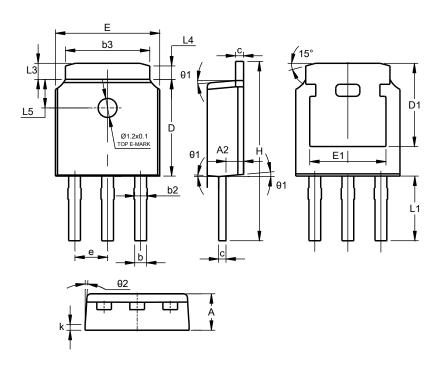






Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



TO251 (Type TH2)							
Dim	Min	Max	Тур				
Α	2.20	2.40	2.30				
A2	0.97	1.17	1.07				
b	0.68	0.90	0.78				
b2	0.76	0.95	0.84				
b3	5.20	5.50	5.33				
С	0.43	0.63	0.53				
D	5.98	6.22	6.10				
D1	5.30 REF						
е	2.	286 BS	C				
Е	6.40	6.80	6.60				
E1	4.63	5.03	4.83				
Н	10.42	10.82	10.62				
k	0.40REF						
L1	3.30	3.70	3.50				
L3	0.88	1.28	1.02				
L4	0.75 REF						
L5	1.65	1.95	1.80				
θ1	5°	9°	7°				
θ2	5°	9°	7°				
All Dimensions in mm							



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